



## Product Change Notice

Micron PCN: 30837  
 Date: 3/1/2013

<b>Type of Change:</b>	Manufacturing Process Change	
<b>Title of Change:</b>	Broad Market eMMC 153/169b Firmware and Manufacturing Changes	
<b>Description of Change:</b>	Broad Market eMMC 153/169b parts will be manufactured with the following changes: <ul style="list-style-type: none"> <li>• Polyimide die coating (new passivation layer) on the NAND die (L74A/L73A) will improve manufacturability of multi-die packages.</li> <li>• New controller version, PS8200FF, will improve the power-on circuit's margin at &lt; -30°C.</li> <li>• New Firmware.</li> <li>• New substrate design will improve signal integrity.</li> </ul>	
<b>Reason for Change:</b>	Optimization of Manufacturing Efficiency and Product Enhancement	
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**Product Affected:** Broad Market eMMC 4GB (J54U), 8GB (J55U), 16GB (J56V), 32GB (J57V), 64GB (J58V)

Affected Micron Part Numbers	Replacement Part Numbers
MTFC4GLVEA-0M WT	MTFC4GLDEA-0M WT
MTFC8GLVEA-4M IT	MTFC8GLDEA-4M IT
MTFC16GJVEC-4M IT	MTFC16GJDEC-4M IT
MTFC32GJVED-4M IT	MTFC32GJDED-4M IT
MTFC64GJVDN-4M IT	MTFC64GJDDN-4M IT
MTFC8GLVEA-1M WT	MTFC8GLDEA-1M WT
MTFC16GJVEC-2M WT	MTFC16GJDEC-2M WT
MTFC32GJVED-3M WT	MTFC32GJDED-3M WT
MTFC64GJVDN-3M WT	MTFC64GJDDN-3M WT

<b>Method of Identification:</b>	<ul style="list-style-type: none"> <li>• Part Numbers change (see table above)</li> <li>• New PRV field in CID register change from "3.x" to "4.x" will identify new controller and firmware version.</li> </ul>
<b>Micron Sites Affected:</b>	Fabrication – FAB2 (Lehi, UT, US), FAB6 (Manassas, VA, US), FAB10 (Singapore) Assembly – Subcontractor

### Product/Data Availability

#### New Production:

*Sample Availability:* Aug 2013  
*Qual Data Availability:* Aug 2013  
*Production Shipments:* Sept 2013

(Continued on next page.)

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change



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**Old Production:**

*Last Time Buy:* Mar 2014  
*Last Time Ship:* Sept 2014

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**Qualification Plan:**

Product manufactured with the changes described above will be qualified according to Company qualification procedure and best practices. Qualification plan will be available upon request.

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Orders placed prior to the LTB date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.